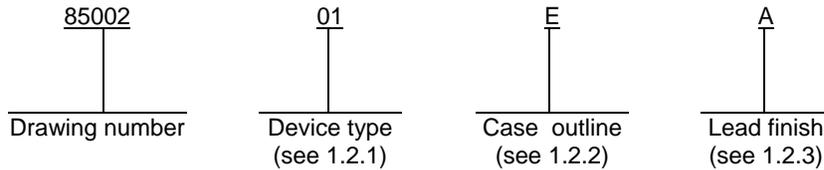




1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device types. The device types identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54HC367	Hex buffer with three-state outputs

1.2.2 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
E	GDIP1-T16 or CDIP2-T16	16	Dual-in-line
F	GDFP2-F16 or CDFP3-F16	16	Flat pack
2	CQCC1-N20	20	Square leadless chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings. <sup>1/</sup>

Supply voltage range ( $V_{CC}$ ) .....	-0.5 V dc to +7.0 V dc
DC input voltage range .....	-0.5 V dc to $V_{CC}$ +0.5 V dc
DC output voltage range .....	-0.5 V dc to $V_{CC}$ +0.5 V dc
DC input diode current .....	$\pm$ 20 mA
DC output diode current .....	$\pm$ 20 mA
DC output current (per pin) .....	$\pm$ 35 mA
DC $V_{CC}$ or ground current (per pin) .....	$\pm$ 70 mA
Maximum power dissipation ( $P_D$ ) .....	500 mW <sup>2/</sup>
Lead temperature (soldering, 10 seconds) .....	+260°C
Thermal resistance, junction-to-case ( $\theta_{JC}$ ) .....	See MIL-STD-1835
Junction temperature ( $T_J$ ) .....	+175°C
Storage temperature range ( $T_{STG}$ ) .....	-65°C to +150°C

1.4 Recommended operating conditions.

Supply voltage range ( $V_{CC}$ ) .....	+2.0 V dc to +6.0 V dc
Case operating temperature range ( $T_C$ ) .....	-55°C to +125°C
Input rise or fall time:	
$V_{CC}$ = 2.0 V .....	0 to 1000 ns
$V_{CC}$ = 4.5 V .....	0 to 500 ns
$V_{CC}$ = 6.0 V .....	0 to 400 ns

<sup>1/</sup> Unless otherwise specified, all voltages are referenced to ground.

<sup>2/</sup> For  $T_C$  = +100°C to +125°C, derate linearly at 12 mW/°C.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 2

## 2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

### DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

### DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

### DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <https://assist.daps.dla.mil/quicksearch/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Non-Government publications. The following document(s) form a part of this document to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

### JEDEC – SOLID STATE TECHNOLOGY ASSOCIATION (JEDEC)

JESD 7-A - Standard for Description of 54/74HCXXXX and 54/74HCTXXXX High-Speed CMOS Devices

(Copies of these documents are available online at <http://www.jedec.org> or from JEDEC – Solid State Technology Association, 3103 North 10th Street, Suite 240–S, Arlington, VA 22201.)

2.3 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

## 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 3

3.2.5 Switching waveforms and test circuit. The switching waveforms and test circuit shall be as specified on figure 4.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein).

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 and QML-38535 (see 6.6 herein). The certificate of compliance submitted to DLA Land and Maritime -VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DLA Land and Maritime-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DLA Land and Maritime, DLA Land and Maritime 's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 4

Table I. Electrical performance characteristics.

Test	Symbol	Test conditions -55°C ≤ T <sub>C</sub> ≤ +125°C 1/ unless otherwise specified		Group A subgroups	Limits		Unit
					Min	Max	
High-level output voltage	V <sub>OH</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -20 μA	V <sub>CC</sub> = 2.0 V	1, 2, 3	1.9		V
			V <sub>CC</sub> = 4.5 V		4.4		
			V <sub>CC</sub> = 6.0 V		5.9		
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -6.0 mA	V <sub>CC</sub> = 4.5 V	1, 2, 3	3.7		
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OH</sub> = -7.8 mA	V <sub>CC</sub> = 6.0 V		5.2		
Low-level output voltage	V <sub>OL</sub>	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = +20 μA	V <sub>CC</sub> = 2.0 V	1, 2, 3		0.1	V
			V <sub>CC</sub> = 4.5 V		0.1		
			V <sub>CC</sub> = 6.0 V		0.1		
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = +6.0 mA	V <sub>CC</sub> = 4.5 V	1, 2, 3		0.4	
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = +7.8 mA	V <sub>CC</sub> = 6.0 V		0.4		
High-level input voltage	V <sub>IH</sub> 2/		V <sub>CC</sub> = 2.0 V	1, 2, 3	1.5		V
			V <sub>CC</sub> = 4.5 V		3.15		
			V <sub>CC</sub> = 6.0 V		4.2		
Low-level input voltage	V <sub>IL</sub> 2/		V <sub>CC</sub> = 2.0 V	1, 2, 3		0.3	V
			V <sub>CC</sub> = 4.5 V		0.9		
			V <sub>CC</sub> = 6.0 V		1.2		
Input capacitance	C <sub>IN</sub>	V <sub>IN</sub> = 0.0 V, T <sub>C</sub> = +25°C See 4.3.1c		4		10	pF
Quiescent current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND V <sub>CC</sub> = 6.0 V		1, 2, 3		160	μA
Input leakage current	I <sub>IN</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND V <sub>CC</sub> = 6.0 V		1, 2, 3		±1.0	μA
Three-state output leakage current	I <sub>OZ</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND V <sub>CC</sub> = 6.0 V		1, 2, 3		±10.0	μA
Functional tests		See 4.3.1d		7			

See footnotes at end of table.

STANDARD  
MICROCIRCUIT DRAWING  
DLA LAND AND MARITIME  
COLUMBUS, OHIO 43218-3990

SIZE  
A

85002

REVISION LEVEL  
F

SHEET  
5

Table I. Electrical performance characteristics - Continued.

Test	Symbol	Test conditions -55°C ≤ T <sub>C</sub> ≤ +125°C <u>1/</u> unless otherwise specified	Group A subgroups	Limits		Unit	
				Min	Max		
Propagation delay, time, An to Yn	t <sub>PLH</sub> , t <sub>PHL</sub> <u>4/</u>	C <sub>L</sub> = 50 pF See figure 4	V <sub>CC</sub> = 2.0 V	9		120	ns
				10, 11		180	
			V <sub>CC</sub> = 4.5 V	9		24	
				10, 11		36	
			V <sub>CC</sub> = 6.0 V	9		20	
				10, 11		38	
Propagation delay, time, output enable, $\overline{OEn}$ to Yn	t <sub>PZH</sub> , t <sub>PZL</sub>  <u>4/</u>	C <sub>L</sub> = 50 pF See figure 4	V <sub>CC</sub> = 2.0 V	9		190	ns
				10, 11		285	
			V <sub>CC</sub> = 4.5 V	9		38	
				10, 11		57	
			V <sub>CC</sub> = 6.0 V	9		35	
				10, 11		52	
Propagation delay, time, output disable $\overline{OEn}$ to Yn	t <sub>PHZ</sub> , t <sub>PLZ</sub>  <u>4/</u>	C <sub>L</sub> = 50 pF See figure 4	V <sub>CC</sub> = 2.0 V	9		175	ns
				10, 11		265	
			V <sub>CC</sub> = 4.5 V	9		35	
				10, 11		53	
			V <sub>CC</sub> = 6.0 V	9		31	
				10, 11		46	
Transition time, output rise and fall times	t <sub>THL</sub> , t <sub>TLH</sub>  <u>4/</u>	C <sub>L</sub> = 50 pF See figure 4	V <sub>CC</sub> = 2.0 V	9		60	ns
				10, 11		90	
			V <sub>CC</sub> = 4.5 V	9		12	
				10, 11		18	
			V <sub>CC</sub> = 6.0 V	9		10	
				10, 11		15	

1/ For a power supply of 5.0 V ±10% the worst case output voltage (V<sub>OH</sub> and V<sub>OL</sub>) occur for HC at 4.5 V. Thus, the 4.5 V values should be used when designed with this supply. Worst case V<sub>IN</sub> and V<sub>IL</sub> occur at V<sub>CC</sub> = 5.5 V and 4.5 V, respectively. (The V<sub>IH</sub> value at V<sub>CC</sub> = 5.5 V is 3.85 V.) The worst case leakage current (I<sub>IN</sub>, I<sub>CC</sub>, and I<sub>OZ</sub>) occur for CMOS at the higher voltage so the 6.0 V values should be used. Power dissipation capacitance (C<sub>PD</sub>), typically 150 pF, determines the no load dynamic power consumption, P<sub>D</sub> = C<sub>PD</sub> V<sub>CC</sub><sup>2</sup> f + I<sub>CC</sub> V<sub>CC</sub>; and the no load dynamic current consumption, I<sub>S</sub> = C<sub>PD</sub> V<sub>CC</sub> f + I<sub>CC</sub>.

2/ V<sub>IH</sub> and V<sub>IL</sub> tests not required if applied as forcing functions for V<sub>OH</sub> or V<sub>OL</sub>.

3/ AC testing at V<sub>CC</sub> = 2.0 V and V<sub>CC</sub> = 6.0 V shall be guaranteed, if not tested, to the limits specified in table I.

4/ Transition times (t<sub>TLH</sub>, t<sub>THL</sub>) shall be guaranteed, if not tested, to the limits specified in table I.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 6

Device type	01	
Case outlines	E and F	2
Terminal number	Terminal symbol	
1	$\overline{OE1}$	NC
2	A1	$\overline{OE1}$
3	Y1	A1
4	A2	Y1
5	Y2	A2
6	A3	NC
7	Y3	Y2
8	GND	A3
9	Y4	Y3
10	A4	GND
11	Y5	NC
12	A5	Y4
13	Y6	A4
14	A6	Y5
15	$\overline{OE2}$	A5
16	V <sub>CC</sub>	NC
17	---	Y6
18	---	A6
19	---	$\overline{OE2}$
20	---	V <sub>CC</sub>

NC = No connection

Pin Description	
Symbol	Description
A <sub>n</sub> (n = 1 to 6)	Data inputs
Y <sub>n</sub> (n = 1 to 6)	Data outputs
$\overline{OE}_n$ (n = 1 or 2)	Output enables (active low)

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 7

Inputs		Outputs
$\overline{OE}_n$	$A_n$	$Y_n$
H	X	Z
X	X	Z
L	H	H
L	L	L

H = High voltage level  
L = Low voltage level  
X = Irrelevant  
Z = High impedance

FIGURE 2. Truth table.

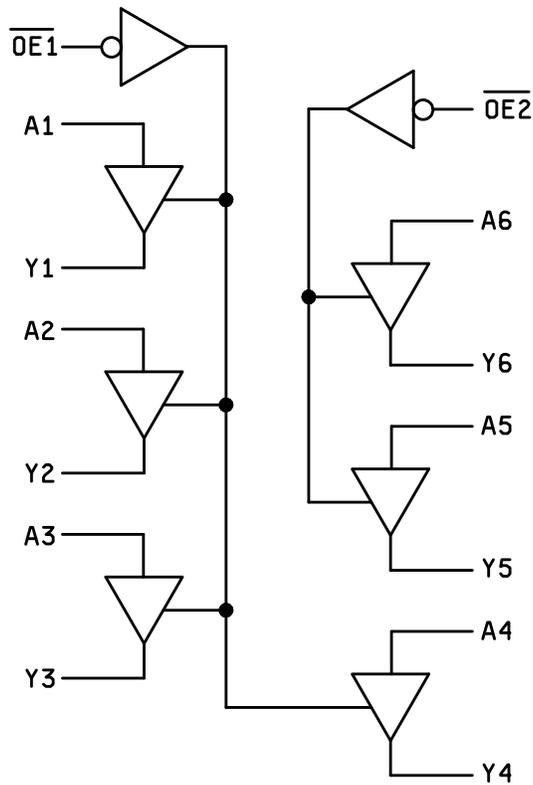


FIGURE 3. Logic diagram.

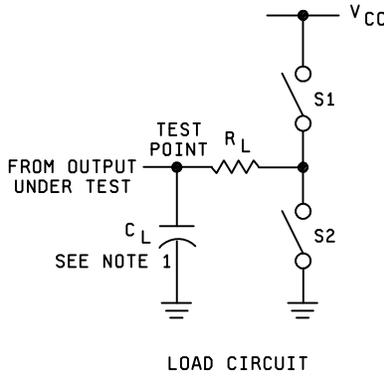
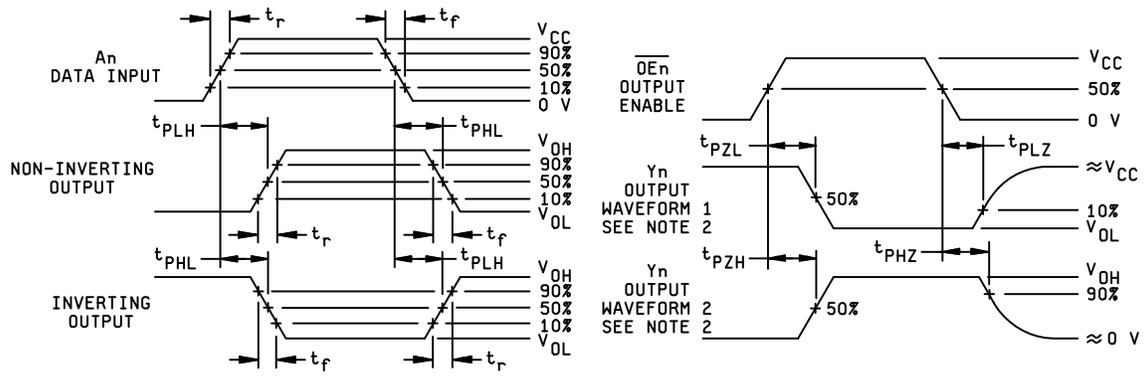
STANDARD  
MICROCIRCUIT DRAWING  
DLA LAND AND MARITIME  
COLUMBUS, OHIO 43218-3990

SIZE  
A

85002

REVISION LEVEL  
F

SHEET  
8



PARAMETER	$R_L$	$C_L$	S1	S2
$t_{PZH}$	1k $\Omega$	50 pF	Open	Closed
$t_{PZL}$			Closed	Open
$t_{PHZ}$	1k $\Omega$	50 pF	Open	Closed
$t_{PLZ}$			Closed	Open
$t_{PLH}, t_{PHL}$ or $t_{THL}, t_{TLH}$	-----	50 pF	Open	Open

NOTES:

- $C_L = 50$  pF minimum or equivalent (includes test jig and probe capacitance).
- Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- $R_L = 1$  k $\Omega$  or equivalent.
- Input signal from pulse generator:  $V_{IN} = 0.0$  V to  $V_{CC}$ ;  $PRR \leq 1$  MHz;  $Z_O = 50\Omega$ ;  $t_r = 6.0$  ns;  $t_f = 6.0$  ns;  $t_r$  and  $t_f$  shall be measured from  $0.1 V_{CC}$  to  $0.9 V_{CC}$  and from  $0.9 V_{CC}$  to  $0.1 V_{CC}$ , respectively; duty cycle = 50 percent.
- Timing parameters shall be tested at a minimum input frequency of 1 MHz.
- The outputs are measured one at a time with one transition per measurement.

FIGURE 4. Switching waveforms and test circuit.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 9

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2)  $T_A = +125^\circ\text{C}$ , minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5, 6 and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 4 ( $C_{IN}$  measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

d. Subgroup 7 shall include verification of the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, B, C, and D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

(2)  $T_A = +125^\circ\text{C}$ , minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 10

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	- - -
Final electrical test parameters (method 5004)	1, 2, 9 <u>1/</u>
Group A test requirements (method 5005)	1, 2, 3, 4, 7, 9, 10, 11 <u>2/</u>
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

1/ PDA applies to subgroup 1.

2/ Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform DLA Land and Maritime when a system application requires configuration control and the applicable SMD. DLA Land and Maritime will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990 or telephone (614) 692-0547.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103 and QML-38535. The vendors listed in MIL-HDBK-103 and QML-38535 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DLA Land and Maritime -VA.

STANDARD MICROCIRCUIT DRAWING DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990	SIZE A		85002
		REVISION LEVEL F	SHEET 11

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 11-07-21

Approved sources of supply for SMD 85002 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DLA Land and Maritime maintains an online database of all current sources of supply at <https://www.landandmaritime.dla.mil/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
8500201EA	01295	SNJ54HC367J
8500201FA	<u>3/</u>	SNJ54HC367W
85002012A	01295	SNJ54HC367FK

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.

2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

3/ Not available from an approved source of supply.

Vendor CAGE number

01295

Vendor name and address

Texas Instruments Incorporated  
Semiconductor Group  
8505 Forest Ln.  
P.O. Box 660199  
Dallas, TX 75243  
Point of contact:

U.S. Highway 75 South  
P.O. Box 84, M/S 853  
Sherman, TX 75090-9493

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